

HSP

NOTES:

Current Rating: 1.0AMP
 Contact Resistance: 20mΩ Max
 Withstand Voltage: 500V AC/DC
 Insulation Resistance: 1000MΩ Min
 Operation Temperature: -40°C to +105°C

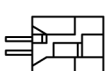
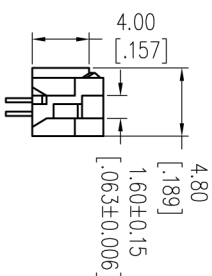
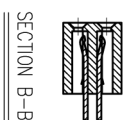
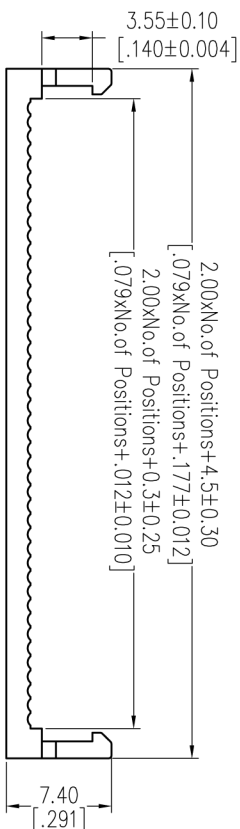
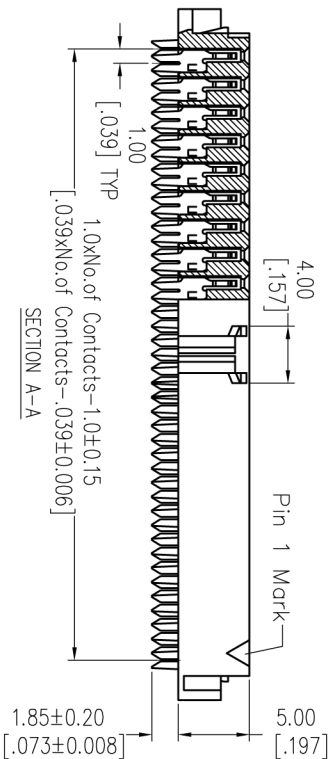
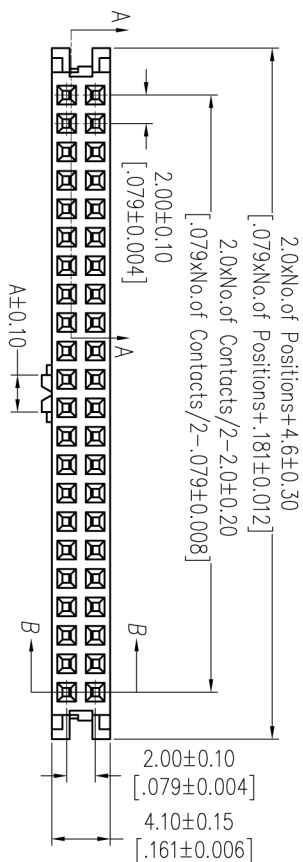
Contact Material: Phosphor Bronze
 Contact plating: Au Or Sn over Ni
 Insulator Material: PBT+30%G.F UL94V-0

Ordering Information

5224-XX YP XX B X 01

No. of Pins Contact Plating Color Insulator Bump
 06P 26P S0=Gold Flash/Ni B=Black N=W/O Bump
 08P 30P S3=10μ"Gold/Ni G=Grey(427C) W=With Bump
 10P 34P S4=15μ"Gold/Ni E=Grey(413C)
 12P 36P S5=30μ"Gold/Ni
 14P 40P SN=Tin
 16P 44P
 18P 50P
 20P 60P
 22P 64P
 24P

| | | |
|-----------|-------|--------|
| Item | Pitch | Mating |
| Standard | 2.00 | 3122 |
| Alternate | | |



| | |
|---------|---------|
| Pin No. | DIM "A" |
| 8P~64P | 2.60 |
| 6P | 2.00 |

| | | |
|-----|------------|--------------------------|
| REV | DATE | MODIFICATION DESCRIPTION |
| A0 | 2012/10/10 | NEW |

| | | | | |
|------------|---------|------------|-------|-----|
| OPERATION | DRAW | DATE | SCALE | FIT |
| XX ±0.40 | JYhuang | 2012/10/10 | UNIT | mm |
| XXX ±0.25 | CHECK | DATE | SIZE | A4 |
| XXXX ±0.15 | APPROVE | DATE | SHEET | 1/1 |
| Angle ± 3' | | | PROJ. | |

| | |
|--------------|--------------------------|
| PART NO. | 5224-XXYPXXXBX01 |
| TITLE: | 2.00 IDC SOCKET (F TYPE) |
| CUSTOMER NO. | |

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